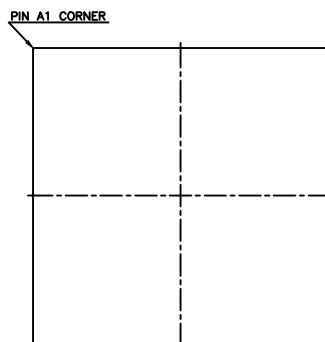
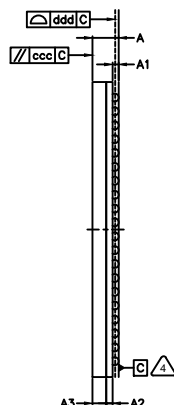


TOP VIEW

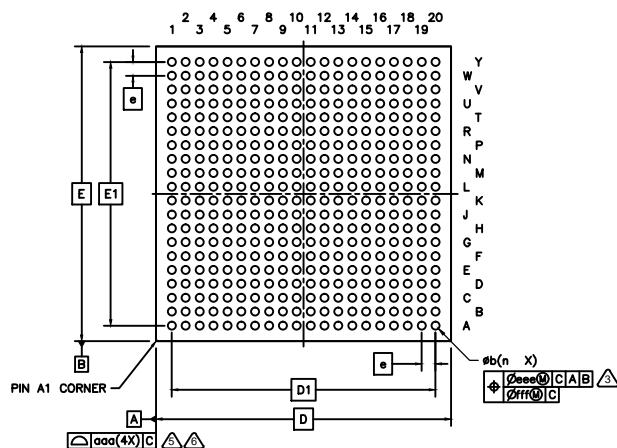


SIDE VIEW



	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Body Size:	X	E	17.000	
	Y	D	17.000	
Ball Pitch:		e	0.800	
Total Thickness:		A	1.320	1.510 1.700
Mold Cap Thickness:		A3	0.800	Ref.
Substrate Thickness:		A2	0.360	Ref.
Ball Diameter:			0.450	
Stand Off:		A1	0.300	0.350 0.400
Ball Width:		b	0.400	0.450
Package Edge Tolerance:		aaa	0.150	
Mold Parallelism:		ccc	0.200	
Coplanarity:		ddd	0.200	
Ball Offset (Package):		eee	0.150	
Ball Offset (Ball):		fff	0.080	
Ball Count:		n	400	
Edge Ball Center to Center:	X	E1	15.200	
	Y	D1	15.200	

BOTTOM VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: JEP95 DR4.5 AND MO-210

Title: Package Outline Drawing	Pkg Type: CABGA	Document No: POD-250080	
Product Family: LFMXO4	Pin Count: 400		
Product Name: LFMXO4-050/080/110-BBG400	Pkg Size: 17x17 mm	Rev: A	

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